

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)				
PCN #: TB1912-02(R1) DATE June 8, 2020 Product Affected: 3mm X 3mm VFQFN 4mm X 4mm VFQFN (Refer to attachment for affected part#) Date Effective: June 8, 2020		MEANS OF DISTINGUISHING CHANGED DEVICES:  Product Mark Back Mark Not applicable Date Code Other		
Contact: PCN DESK E-mail: idt-pcn@lm.renesas.com		Attachment: Samples:	Yes N/A	□ No
DESCRIPTION AND PURPOSE OF CHANGE:  □ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Equipment □ Material □ Testing □ Manufacturing Site □ Data Sheet □ Other - Packaging □ More Technology □ Wafer Fabrication Process □ Revision 1: This revised notice is to retract the changes as stated in the original PCN# TB1912-02 issued in December 20, 2019 after taking customers' input into consideration. With this, changes as stated in the original PCN will not be implemented.  A copy of the original PCN# TB1912-02 is attached for reference.				
RELIABILITY/QUALIFICATION SUMMARY: Not applicable.				
CUSTOMER ACKNOWLEDGMENT IDT records indicate that you require write to grant approval or request additional intit will be assumed that this change is accessibly reserves the right to ship either version the earlier version has been depleted.	tten notification of the formation. If IDT does ptable.	s not receive ackno	owledgement with	in 30 days of this notice
Customer:		Approval f	or shipments p	prior to effective date.
Name/Date:	E	-Mail Address:		
Title:		none# /Fax# :		
CUSTOMER COMMENTS:				
IDT ACKNOWLEDGMENT OF RECEIPT:				
RECD. BY:		DATE:		